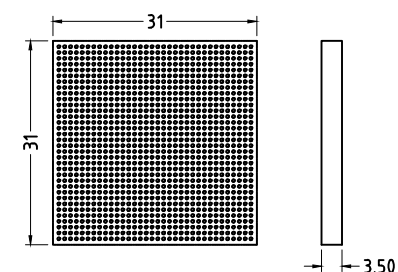
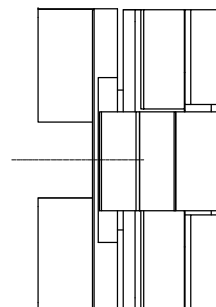
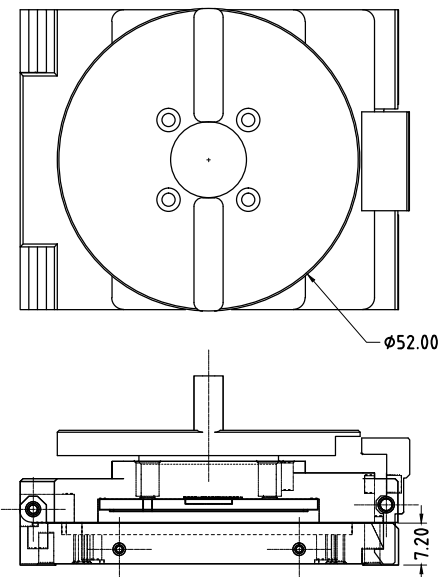
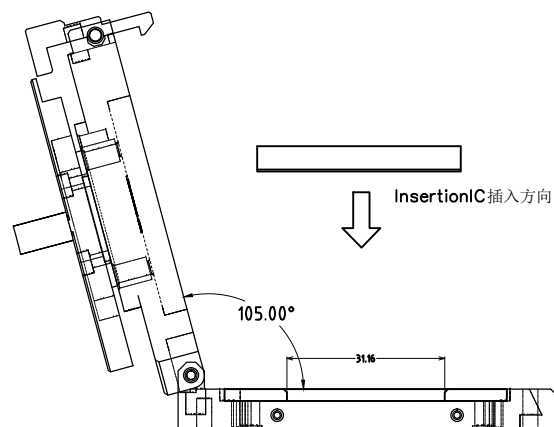


PCB PATTERN (Top View)




Chip

## 1. MATERIAL AND FINISH

1. SOCKET LID :Aluminium alloy
2. SOCKET BASE :Aluminium alloy
3. SOCKET HERNEL :PEI
4. SOCKET LID & SOCKET BASE :Outward anodic tretment
5. CONTACTS :BeCu, SELECTIVE Au-AuFLASH OVER NI PLATING
6. SPRINGS :STAINLESS STEEL ,PASSIVATED

## 2. PERFORMANCE

1. Insulation Resistance : 1000MΩ or more at DC 100V
2. Dielectric Withstanding Voltage: 100V AC for one minute
3. Contact Resistance 50mΩ , MAX. at 10mA and 20mV MAX.(Initial)
4. Operation Temperature -55°C~+125°C
5. Life Span 10,000 Times (Mechanical)
6. Operation Force 3.0 Kg MAX

△ C				DWG NO		PART NAME	BGA900-(31X31)-1.0-CL	
△ B				MATERIAL	SCALE	1:1	TITLE	
△ A				QTY	1	UNIT	mm	
REV	DESCRIPTION	DATE	CHECK	SHEET	1 OF 1	REV	01	
APPLICATION				APPROVE	DATE	 <b>ALLSOCKET</b> www.allsocket.com sales@allsocket.com		
ANGLES	FINISH	ROUGH-EDGE	ME-TRIC	0.X:±0.1	CHECK			DATE
ALL UNSPECIFIED CHAMFERS:C0.2				0.XX:±0.05	DEGK			DATE
								20150204

